



SX3H15-AU

Surface Mount Ultra Low IR Schottky Barrier Rectifier

Voltage **150 V**

Current **3 A**

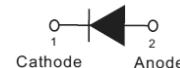
SMA

Features

- Low leakage current
- Ideal for automated placement
- Low power loss, high efficiency
- High surge current capability
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

- Case : SMA Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.0679 grams



Maximum Ratings and Thermal Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNITS
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	150	V
Maximum RMS Voltage	V_{RMS}	105	V
Maximum DC Blocking Voltage	V_{DC}	150	V
Maximum Average Forward Current	$I_{F(AV)}$	3	A
Peak Forward Surge Current : 8.3 ms Single Half Sine-Wave Superimposed On Rated Load	I_{FSM}	80	A
Typical Junction Capacitance Measured at 1 MHZ And Applied $V_R = 4 \text{ V}$	C_J	95	pF
Typical Thermal Resistance (Note 1) (Note 2)	$R_{\theta JA}$	150	
	$R_{\theta JC}$	22	$^\circ\text{C}/\text{W}$
	$R_{\theta JL}$	15	
Operating Junction Temperature Range	T_J	-55~175	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55~175	$^\circ\text{C}$



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Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Forward Voltage	V_F	$I_F = 1 \text{ A}, T_J = 25^\circ\text{C}$	-	0.7	-	V
		$I_F = 1.5 \text{ A}, T_J = 25^\circ\text{C}$	-	0.73	-	V
		$I_F = 3 \text{ A}, T_J = 25^\circ\text{C}$	-	-	0.85	V
		$I_F = 1 \text{ A}, T_J = 125^\circ\text{C}$	-	0.56	-	V
		$I_F = 1.5 \text{ A}, T_J = 125^\circ\text{C}$	-	0.59	-	V
		$I_F = 3 \text{ A}, T_J = 125^\circ\text{C}$	-	0.65	-	V
Reverse Current ^(Note 3)	I_R	$V_R = 120 \text{ V}, T_J = 25^\circ\text{C}$	-	0.039	-	uA
		$V_R = 150 \text{ V}, T_J = 25^\circ\text{C}$	-	-	0.5	
		$V_R = 150 \text{ V}, T_J = 125^\circ\text{C}$	-	-	1	mA

NOTES :

1. Mounted on a FR4 PCB, single-sided copper, standard footprint.
2. Mounted on a FR4 PCB, single-sided copper, with 100 cm² copper pad area.
3. Short duration pulse test used to minimize self-heating effect.



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TYPICAL CHARACTERISTIC CURVES

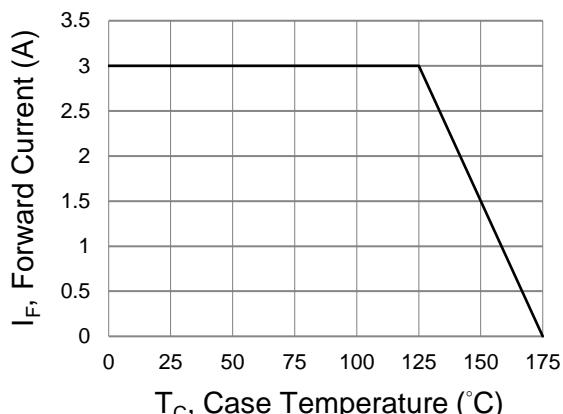


Fig.1 Forward Current Derating Curve

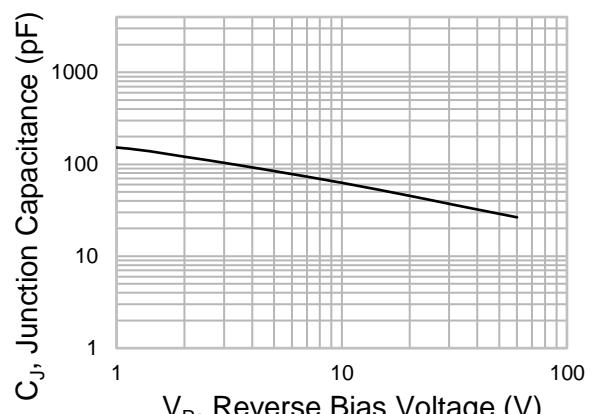


Fig.2 Typical Junction Capacitance

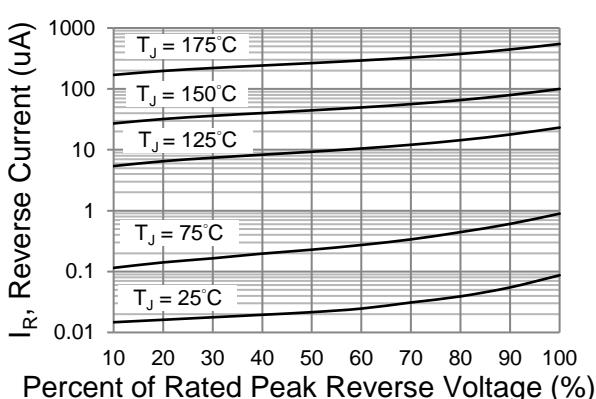


Fig.3 Typical Reverse Characteristics

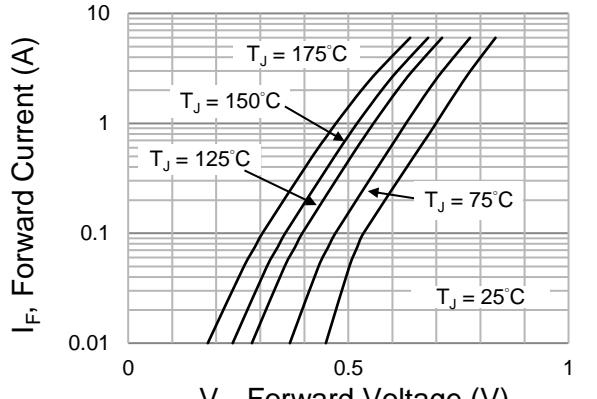


Fig.4 Typical Forward Characteristics

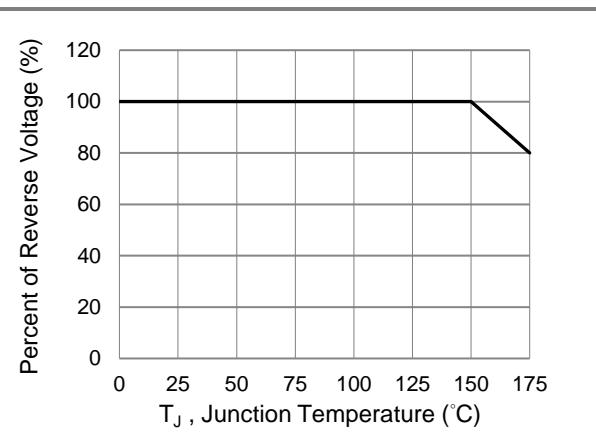


Fig.5 Operating Temperature Derating Curve



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Part No. Packing Code Version

Part No. Packing Code	Package Type	Packing Type	Marking	Version
SX3H15-AU	SMA	7.5K pcs / 13" reel	SX3H15	Halogen free RoHS compliant

Packaging Information & Mounting Pad Layout

